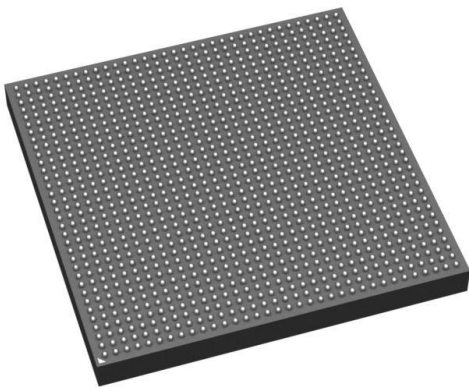


XCZU57DR-L1FSVE1156I Datasheet

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XCZU57DR-L1FSVE1156I

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DiGi Electronics Part Number	XCZU57DR-L1FSVE1156I-DG
Manufacturer	AMD
Manufacturer Product Number	XCZU57DR-L1FSVE1156I
Description	IC ZUP RFSOC A53 FPGA LP 1156BGA
Detailed Description	Quad ARM® Cortex®-A53 MPCore™ with CoreSight™, Dual ARM®Cortex™-R5 with CoreSight™ System On Chip (SOC) IC Zynq® UltraScale+™ RFSoc DR Zynq® UltraScale+™ RFSoc 500MHz, 1.2GHz 1156-FCBGA (35x35)



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DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

XCZU57DR-L1FSVE1156I

Series:

Zynq® UltraScale+™ RFSoc DR

Architecture:

MPU, FPGA

Flash Size:

-

Peripherals:

DDR, DMA, PCIe, WDT

Speed:

500MHz, 1.2GHz

Operating Temperature:

-40°C ~ 100°C (Tj)

Supplier Device Package:

1156-FCBGA (35x35)

Manufacturer:

AMD

Product Status:

Active

Core Processor:

Quad ARM® Cortex®-A53 MPCore™ with CoreSight™, Dual ARM®Cortex™-R5 w

RAM Size:

-

Connectivity:

CANbus, EBI/EMI, Ethernet, I2C, MMC/SD/SDIO, SPI, UART/USART, USB OTG

Primary Attributes:

Zynq® UltraScale+™ RFSoc

Package / Case:

1156-BBGA, FCBGA

Number of I/O:

-

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

Moisture Sensitivity Level (MSL):

4 (72 Hours)



Additional Nanya Substrate Supplier for UltraScale & UltraScale+ Monolithic Packages

XCN20014 (v1.4) May 10, 2021

Product Change Notice

Overview

The purpose of this notification is to announce Xilinx® will include Nanya as additional substrate supplier for Xilinx Kintex® UltraScale™, Kintex® UltraScale+™, Virtex® UltraScale+™ and Zynq® UltraScale+™ commercial / industrial “XC” and automotive “XA” grade devices. Defense-grade “XQ” device-packages are not affected by this PCN.

Description

Due to recent supply chain continuity and force majeure, Xilinx has completed package qualification and will be shipping Nanya substrate for monolithic packages, as additional substrate for Xilinx Kintex UltraScale, Kintex UltraScale+, Virtex UltraScale+ and Zynq UltraScale+ commercial / industrial “XC” and automotive “XA” grade devices. Nanya substrate has been used for more than 20 years in industry and has been considered a stable substrate supplier. This additional supplier will adhere to the same performance, quality and reliability specifications that apply to all product families proven through extensive qualification and testing. There are no changes to form, fit, function, or reliability.

Products Affected

This change affects all speeds and temperature grades such as commercial / industrial “XC” and automotive “XA” in all speed grade devices (refer to tables below). Any associated specification control document (SCD) versions of the standard part numbers are also affected.

Table 1: Phase 1 Products Affected (Body size smaller or equal than 27x27mm)

Kintex UltraScale+

Device	Package
XCKU3P	FFVA676
XCKU3P	FFVB676
XCKU3P	SFVB784
XCKU5P	FFVA676
XCKU5P	FFVB676
XCKU5P	SFVB784

Zynq UltraScale+

Device	Package
XCZU2CG	SBVA484
XCZU2CG	SFVA625
XCZU2CG	SFVC784
XCZU2EG	SBVA484
XCZU2EG	SFVA625
XCZU2EG	SFVC784
XCZU3CG	SBVA484
XCZU3CG	SFVA625
XCZU3CG	SFVC784

Device	Package
XCZU3EG	SBVA484
XCZU3EG	SFVA625
XCZU3EG	SFVC784
XCZU4CG	SFVC784
XCZU4EG	SFVC784
XCZU4EV	SFVC784
XCZU5CG	SFVC784
XCZU5EG	SFVC784
XCZU5EV	SFVC784

Additional Nanya Substrate Supplier for UltraScale & UltraScale+ Monolithic Products
Table 2: Phase 2 Products Affected (Body size larger than 27x27mm)
Kintex UltraScale+

Device	Package
XCKU3P	FFVD900
XCKU5P	FFVD900
XCKU9P	FFVE900
XCKU11P	FFVA1156
XCKU11P	FFVD900
XCKU11P	FFVE1517
XCKU13P	FFVE900
XCKU15P	FFVA1156
XCKU15P	FFVA1760
XCKU15P	FFVE1517
XCKU15P	FFVE1760
XCKU19P	FFVB2104
XCKU19P	FFVJ1760

Virtex UltraScale+

Device	Package
XCVU3P	FFVC1517
XCVU23P	FSVJ1760
XCVU23P	VSVA1365

Zynq UltraScale+

Device	Package
XCZU4CG	FBVB900
XCZU4EG	FBVB900
XCZU4EV	FBVB900
XCZU5CG	FBVB900
XCZU5EG	FBVB900
XCZU5EV	FBVB900
XCZU6CG	FFVC900
XCZU6CG	FFVB1156
XCZU6EG	FFVC900
XCZU6EG	FFVB1156
XCZU7CG	FBVB900
XCZU7CG	FFVF1517
XCZU7CG	FFVC1156

Zynq UltraScale+ (Con't)

Device	Package
XCZU7EG	FBVB900
XCZU7EG	FFVC1156
XCZU7EG	FFVF1517
XCZU7EV	FBVB900
XCZU7EV	FFVC1156
XCZU7EV	FFVF1517
XCZU9CG	FFVC900
XCZU9CG	FFVB1156
XCZU9EG	FFVC900
XCZU9EG	FFVB1156
XCZU11EG	FFVC1156
XCZU11EG	FFVC1760
XCZU11EG	FFVF1517
XCZU11EG	FFVB1517
XCZU15EG	FFVC900
XCZU15EG	FFVB1156
XCZU17EG	FFVB1517
XCZU17EG	FFVC1760
XCZU17EG	FFVD1760
XCZU17EG	FFVE1924
XCZU19EG	FFVB1517
XCZU19EG	FFVC1760
XCZU19EG	FFVE1924
XCZU19EG	FFVD1760
XCZU21DR	FFVD1156
XCZU21DR	FSVD1156
XCZU25DR	FFVE1156
XCZU25DR	FFVG1517
XCZU25DR	FSVE1156
XCZU25DR	FSVG1517
XCZU27DR	FFVE1156
XCZU27DR	FFVG1517
XCZU27DR	FSVE1156
XCZU27DR	FSVG1517
XCZU28DR	FFVE1156
XCZU28DR	FFVG1517
XCZU28DR	FSVG1517

Zynq UltraScale+ (Con't)

Device	Package
XCZU28DR	FSVE1156
XCZU29DR	FFVF1760
XCZU29DR	FSVF1760
XCZU39DR	FFVF1760
XCZU39DR	FSVF1760
XCZU42DR	FFVE1156
XCZU42DR	FSVE1156
XCZU43DR	FFVE1156
XCZU43DR	FFVG1517
XCZU43DR	FSVE1156
XCZU43DR	FSVG1517
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XCZU58DR	FFVE1156
XCZU58DR	FFVG1517
XCZU58DR	FSVE1156
XCZU58DR	FSVG1517
XCZU59DR	FFVF1760
XCZU59DR	FSVF1760
XCZU65DR	FFVE1156
XCZU65DR	FSVE1156
XCZU67DR	FFVE1156
XCZU67DR	FSVE1156

**Table 3: Phase 3 Products Affected (XA)****Zynq UltraScale+**

Device	Package
XAZU2EG	SBVA484
XAZU2EG	SFVA625
XAZU2EG	SFVC784
XAZU3EG	SBVA484
XAZU3EG	SFVA625
XAZU3EG	SFVC784

Device	Package
XAZU4EV	SFVC784
XAZU5EV	SFVC784
XAZU7EV	FBVB900
XAZU11EG	FFVF1517

Table 4: Phase 4 Products Affected (20nm XC)**Kintex UltraScale**

Device	Package
XCKU035	FBVA676
XCKU040	FBVA676
XCKU025	FFVA1156
XCKU035	FFVA1156
XCKU040	FFVA1156
XCKU060	FFVA1156

Key Dates and Ordering Information

Xilinx will begin to ship products with Nanya substrate as listed in the phases described below:

Phase 1: Starting by **Feb 1st, 2021** for Xilinx UltraScale+ devices listed in [Table 1](#)

Phase 2: Starting by **May 1st, 2021** for Xilinx UltraScale+ devices listed in [Table 2](#)

Phase 3: Starting by **June 20th, 2021** for Xilinx UltraScale+ devices listed in [Table 3](#)

Phase 4: Starting by **June 20th, 2021** for Xilinx UltraScale devices listed in [Table 4](#)

Qualification Data

Qualification data is available upon request.

Required Action

Acknowledgement required within 30 days of receipt of this notice. No feedback or response of the PCN within 30 days constitutes acceptance of the change. For additional information or questions, please contact your Xilinx sales representative.

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
11/30/2020	1.0	Initial release.
11/30/2020	1.1	Updated Table 1 .
12/14/2020	1.2	Updated Table 1 and Table 2 .
03/22/2021	1.3	Added Table 3 with XA products. Updated Phase 2 dates.
05/10/2021	1.4	Added Table 4 with 20nm XC products.

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